

DIN-Signal 2C048MR-3,0C1-2-clip

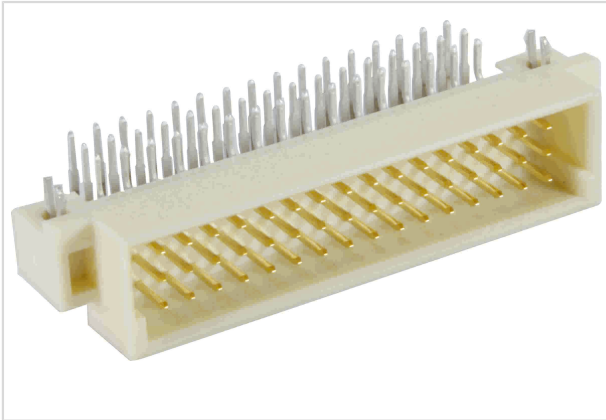


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Part number	09 23 348 6919
Specification	DIN-Signal 2C048MR-3,0C1-2-clip
HARTING eCatalogue	https://b2b.harting.com/09233486919

Identification

Category	Connectors
Series	DIN 41612
Identification	Type 2C
Element	Male connector
Description of the contact	Angled
Features	lead-free Colour deviations and speckles permitted

Version

Termination method	Reflow soldering termination (THR)
Connection type	Motherboard to daughtercard Extender card PCB to cable
Number of contacts	48
Contact configuration	Rows a, b and c, positions 1, 2, ... , 15, 16
Coding	Coding with loss of contacts
PCB fixing	With fixing flange With snap-in clip

Technical characteristics

Contact rows	3
Contact spacing (termination side)	2.54 mm
Contact spacing (mating side)	2.54 mm
Rated current	2 A



Pushing Performance
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Technical characteristics

Rated current	Rated current measured at 20 °C, see derating curve for details
Clearance distance	≥1.2 mm
Creepage distance	≥1.2 mm
Insulation resistance	>10 ¹² Ω
Contact resistance	≤20 mΩ
Limiting temperature	-55 ... +125 °C (during reflow soldering max. +240 °C for 15 s)
Insertion and withdrawal force	≤45 N
Performance level	2 acc. to IEC 60603-2
Mating cycles	≥400
Test voltage U _{r.m.s.}	1 kV
Isolation group	II (400 ≤ CTI < 600)
PCB thickness	1.6 mm ±0.2
Hot plugging	No

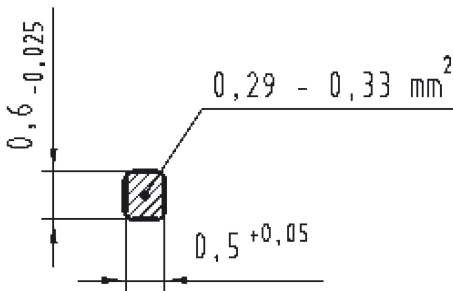
Material properties

Material (insert)	Thermoplastic resin, glass-fibre filled
Colour (insert)	Beige
Material (contacts)	Copper alloy
Surface (contacts)	Noble metal over Ni Mating side Sn over Ni Termination side
Material flammability class acc. to UL 94	V-0
RoHS	compliant
ELV status	compliant
China RoHS	e
REACH Annex XVII substances	Not contained
REACH ANNEX XIV substances	Not contained
REACH SVHC substances	Not contained
California Proposition 65 substances	Yes
California Proposition 65 substances	Lead Nickel
Requirement set with Hazard Levels	R26

Specifications and approvals

Specifications	IEC 60603-2 (complementary)
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Cross section of solder termination



Quantity of solder paste

Before the components are assembled, solder paste must be applied to all the solder pads (for connecting surface-mount components) and the plated through holes. To ensure that the plated through holes are completely filled, significantly more solder paste must be applied than traditional solder pads on the pcb surface. There are numerous calculation methods available which are complicated to apply. The following rule of thumb has proved valuable in practice.

Required volume of paste = 2 (Volume of plated through hole - Volume of the connector termination in the hole)

Comment: the multiplier "2" compensates for solder paste shrinkage during soldering. For this purpose, it was assumed that 50% of the paste consists of the actual solder, the other 50% being soldering aids.

Soldering instructions

THR (ThroughHoleReflow) connectors are designed to be used in a reflow oven together with other SMD (SurfaceMountDevice) components. In the process, called as well "Pin in Hole Intrusive Reflow", the connectors are inserted into plated through holes in a comparable way to conventional component mounting. All other components can be assembled on the pcb surface.

The length of the connector contacts should be such that they protrude by no more than 1.5 millimetres after insertion to the pcb. Each contact collects solder on its tip as it penetrates the solder paster in the hole. So if the contact is too long, this solder would no longer be able to reflow back into the plated through hole by capillary action during the soldering process, therefore the quality of the soldered connection would suffer as a result.

Mating conditions



To ensure reliable connections and prevent unnecessary damage, please refer to the application data diagrams. These recommendations are set out in IEC 60603-2. The connectors should not be coupled and decoupled under electrical load.